RABS2 THRU RABS10

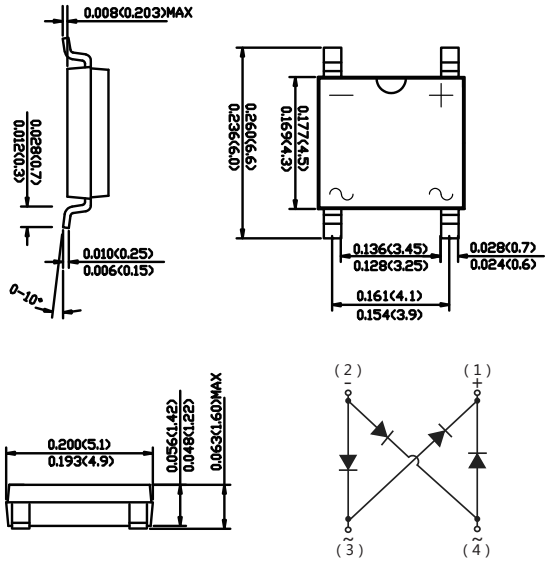
Voltage Range - 200 to 1000 V olts Current - 0.8/1.0 Ampere

GLASS PASSIVATED FAST RECOVERY BRIDGE RECTIFIERS

Features

ABS RoHS COMPLIANT

- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- High temperature soldering guaranteed: 260°/10 seconds at 5 lbs., (2.3kg) tension
- Small size, simple installation
- High surge current capability
- Glass passivated chip junction
- Leads solderable per MIL-STD-202, Method 208



Mechanical Data

Case : JEDEC ABS Molded plastic body
Terminals : Solder plated, solderable per MIL-STD-750,Method 2026
Polarity : Polarity symbol marking on body
Mounting Position : Any
Weight : 0.003 ounce, 0.098 grams

Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unle ss otherwise specified.

Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

Parameter	SYMBOLS	RABS2	RABS4	RABS6	RABS8	RABS10	UNITS
Marking Code		MDD RABS2	MDD RABS4	MDD RABS6	MDD RABS8	MDD RABS10	
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	200	400	600	800	1000	V
Maximum average forward rectified current On glass-epoxy P.C.B.(Note1) On aluminum substrate(Note2)	$I_{F(AV)}$	0.8 1.0					A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30					A
Maximum instantaneous forward voltage drop per leg at 0.4A	V_F	1.3					V
Maximum DC reverse current T_A=25°C at rated DC blocking voltage T_A=100°C	I_R	5 500					uA uA
Typical thermal resistance(NOTE 3)	$R\theta_{JL}$ $R\theta_{JA}$	25 75					°C/W
Maximum reverse recovery time (NOTE 4)	trr	150		250	500		ns
Operating temperature range	T_J	-55 to +150					°C
storage temperature range	T_{STG}	-55 to +150					°C

NOTES:1.On glass epoxy P.C.B. mounted on 0.05x0.05"(1.3x1.3mm) pads.
2.On aluminum substrate P.C.B. with an area of 0.8"x0.8"(20x20mm) mounted on 0.05X0.05"(1.3X1.3mm) solder pad.
3.Thermal resistance form junction to ambient and junction to lead mounted on P.C.B. with 0.2X0.2"(5X5mm) copper pads.
4.Reverse recovery condition I_F=0.5A,I_R=1.0A,Irr=0.25A.

Ratings And Characteristic Curves

FIG.1 FORWARD DERATING CURVE

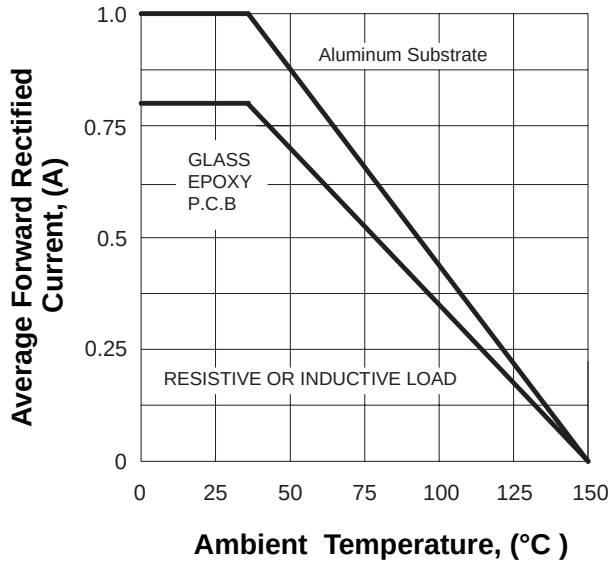


FIG.2 PEAK FORWARD SURGE CURRENT

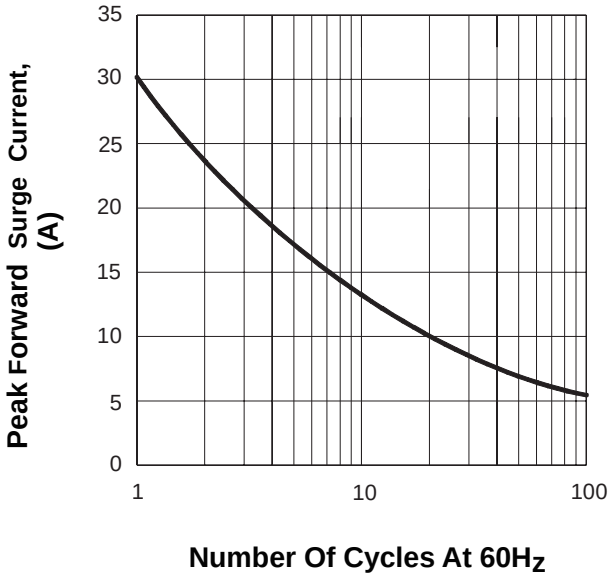


FIG.3 TYPICAL FORWARD CHARACTERISTICS

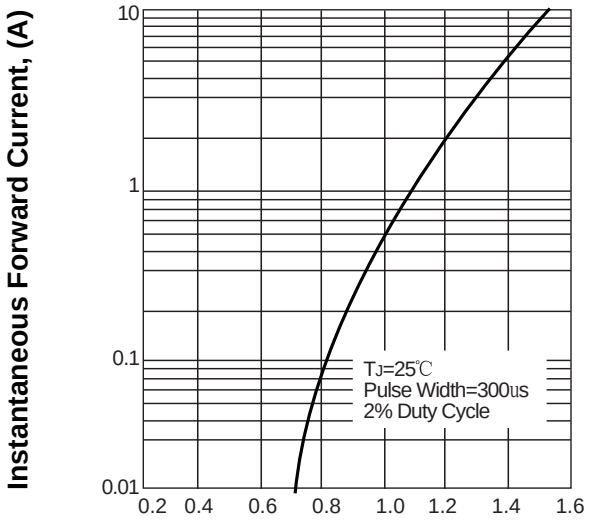
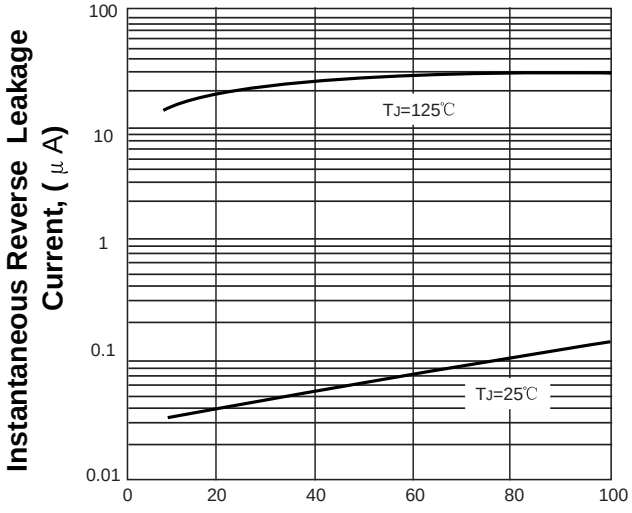
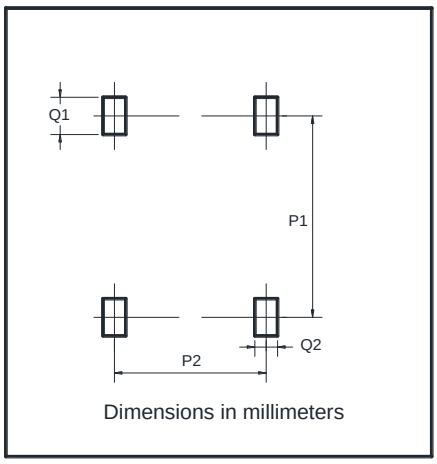


FIG.4 TYPICAL REVERSE CHARACTERISTICS



The curve above is for reference only.

Suggested Pad Layout



Dim	Min
P1	5.72
P2	4.00
Q1	1.00
Q2	0.90

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